# **Hex Schmitt Trigger**

The MC14584B Hex Schmitt Trigger is constructed with MOS P-channel and N-channel enhancement mode devices in a single monolithic structure. These devices find primary use where low power dissipation and/or high noise immunity is desired. The MC14584B may be used in place of the MC14069UB hex inverter for enhanced noise immunity to "square up" slowly changing waveforms.

- Supply Voltage Range = 3.0 Vdc to 18 Vdc
- Capable of Driving Two Low–power TTL Loads or One Low–power Schottky TTL Load over the Rated Temperature Range
- Double Diode Protection on All Inputs
- Can Be Used to Replace MC14069UB
- For Greater Hysteresis, Use MC14106B which is Pin–for–Pin Replacement for CD40106B and MM74Cl4

### MAXIMUM RATINGS (Voltages Referenced to V<sub>SS</sub>) (Note 2.)

Symbol	Parameter	Value	Unit
$V_{DD}$	DC Supply Voltage Range	-0.5 to +18.0	V
V <sub>in</sub> , V <sub>out</sub>	nput or Output Voltage Range		V
I <sub>in</sub> , I <sub>out</sub>	Input or Output Current (DC or Transient) per Pin	±10	mA
P <sub>D</sub>	Power Dissipation, per Package (Note 3.)	500	mW
T <sub>A</sub>	Ambient Temperature Range	-55 to +125	°C
T <sub>stg</sub>	Storage Temperature Range	-65 to +150	°C
TL	Lead Temperature (8–Second Soldering)	260	°C

- Maximum Ratings are those values beyond which damage to the device may occur.
- Temperature Derating: Plastic "P and D/DW" Packages: – 7.0 mW/°C From 65°C To 125°C

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high–impedance circuit. For proper operation,  $V_{in}$  and  $V_{out}$  should be constrained to the range  $V_{SS} \leq (V_{in} \text{ or } V_{out}) \leq V_{DD}.$ 

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either  $V_{SS}$  or  $V_{DD}$ ). Unused outputs must be left open.

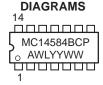


### ON Semiconductor

http://onsemi.com



PDIP-14 P SUFFIX CASE 646



**MARKING** 



SOIC-14 D SUFFIX CASE 751A





TSSOP-14 DT SUFFIX CASE 948G



14



SOEIAJ-14 F SUFFIX CASE 965



A = Assembly Location

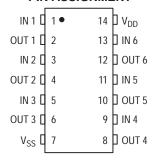
WL or L = Wafer Lot YY or Y = Year WW or W = Work Week

### ORDERING INFORMATION

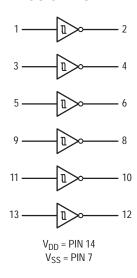
Device	Package	Shipping
MC14584BCP	PDIP-14	2000/Box
MC14584BD	SOIC-14	55/Rail
MC14584BDR2	SOIC-14	2500/Tape & Reel
MC14584BDT	TSSOP-14	96/Rail
MC14584BDTEL	TSSOP-14	2000/Tape & Reel
MC14584BF	SOEIAJ-14	See Note 1.
MC14584BFEL	SOEIAJ-14	See Note 1.

 For ordering information on the EIAJ version of the SOIC packages, please contact your local ON Semiconductor representative.

### **PIN ASSIGNMENT**

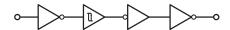


### **LOGIC DIAGRAM**



### **EQIVALENT CIRCUIT SCHEMATIC**

(1/6 OF CIRCUIT SHOWN)



### **ELECTRICAL CHARACTERISTICS** (Voltages Referenced to V<sub>SS</sub>)

			V <sub>DD</sub>	- 5	5°C		25°C		125	i∘C	
Characterist	tic	Symbol	Vdc	Min	Max	Min	Typ <sup>(4.)</sup>	Max	Min	Max	Unit
Output Voltage V <sub>in</sub> = V <sub>DD</sub>	"0" Level	V <sub>OL</sub>	5.0 10 15	_ _ _	0.05 0.05 0.05	_ _ _	0 0 0	0.05 0.05 0.05	_ _ _	0.05 0.05 0.05	Vdc
V <sub>in</sub> = 0	"1" Level	V <sub>OH</sub>	5.0 10 15	4.95 9.95 14.95	_ _ _	4.95 9.95 14.95	5.0 10 15	_ _ _	4.95 9.95 14.95	_ _ _	Vdc
Output Drive Current $ (V_{OH} = 2.5 \text{ Vdc}) $ $ (V_{OH} = 4.6 \text{ Vdc}) $ $ (V_{OH} = 9.5 \text{ Vdc}) $ $ (V_{OH} = 13.5 \text{ Vdc}) $	Source	I <sub>OH</sub>	5.0 5.0 10 15	- 3.0 - 0.64 - 1.6 - 4.2		- 2.4 - 0.51 - 1.3 - 3.4	- 4.2 - 0.88 - 2.25 - 8.8		- 1.7 - 0.36 - 0.9 - 2.4		mAdc
$(V_{OL} = 0.4 \text{ Vdc})$ $(V_{OL} = 0.5 \text{ Vdc})$ $(V_{OL} = 1.5 \text{ Vdc})$	Sink	l <sub>OL</sub>	5.0 10 15	0.64 1.6 4.2		0.51 1.3 3.4	0.88 2.25 8.8	  -  -	0.36 0.9 2.4		mAdc
Input Current		l <sub>in</sub>	15	_	±0.1	_	±0.00001	±0.1	_	±1.0	μAdc
Input Capacitance (V <sub>in</sub> = 0)		C <sub>in</sub>	_	_	_	_	5.0	7.5	_	_	pF
Quiescent Current (Per Package)		I <sub>DD</sub>	5.0 10 15	_ _ _	0.25 0.5 1.0		0.0005 0.0010 0.0015	0.25 0.5 1.0	_ _ _	7.5 15 30	μAdc
Total Supply Current (5.) (6.) (Dynamic plus Quiescent, Per Package) (C <sub>L</sub> = 50 pF on all outputs, all buffers switching)		Ι <sub>Τ</sub>	5.0 10 15			$I_{T} = (3$	1.8 μΑ/kHz) f 3.6 μΑ/kHz) f 5.4 μΑ/kHz) f	+ I <sub>DD</sub>			μAdc
Hysteresis Voltage		V <sub>H</sub> <sup>(7.)</sup>	5.0 10 15	0.27 0.36 0.77	1.0 1.3 1.7	0.25 0.3 0.6	0.6 0.7 1.1	1.0 1.2 1.5	0.21 0.25 0.50	1.0 1.2 1.4	Vdc
Threshold Voltage Positive–Going		V <sub>T+</sub>	5.0 10 15	1.9 3.4 5.2	3.5 7.0 10.6	1.8 3.3 5.2	2.7 5.3 8.0	3.4 6.9 10.5	1.7 3.2 5.2	3.4 6.9 10.5	Vdc
Negative-Going		V <sub>T-</sub>	5.0 10 15	1.6 3.0 4.5	3.3 6.7 9.7	1.6 3.0 4.6	2.1 4.6 6.9	3.2 6.7 9.8	1.5 3.0 4.7	3.2 6.7 9.9	Vdc

<sup>4.</sup> Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.

$$I_T(C_L) = I_T(50 \text{ pF}) + (C_L - 50) \text{ Vfk}$$

where:  $I_T$  is in  $\mu A$  (per package),  $C_L$  in pF,  $V = (V_{DD} - V_{SS})$  in volts, f in kHz is input frequency, and k = 0.001.

7.  $V_H = V_{T+} - V_{T-}$  (But maximum variation of  $V_H$  is specified as less than  $V_{T+max} - V_{T-min}$ ).

<sup>5.</sup> The formulas given are for the typical characteristics only at 25°C.6. To calculate total supply current at loads other than 50 pF:

# SWITCHING CHARACTERISTICS ( $C_L = 50 \text{ pF}, T_A = 25^{\circ}C$ )

Characteristic	Symbol	V <sub>DD</sub> Vdc	Min	Typ <sup>(8.)</sup>	Max	Unit
Output Rise Time	t <sub>TLH</sub>	5.0 10 15	_ _ _	100 50 40	200 100 80	ns
Output Fall Time	t <sub>THL</sub>	5.0 10 15	_ _ _	100 50 40	200 100 80	ns
Propagation Delay Time	t <sub>PLH</sub> , t <sub>PHL</sub>	5.0 10 15	_ _ _	125 50 40	250 100 80	ns

<sup>8.</sup> Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.

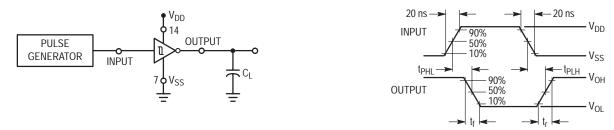
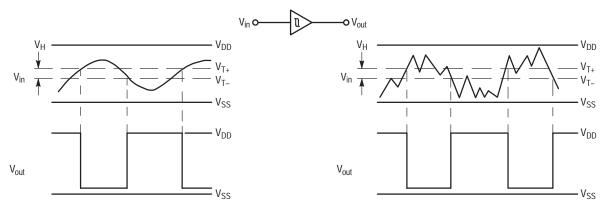


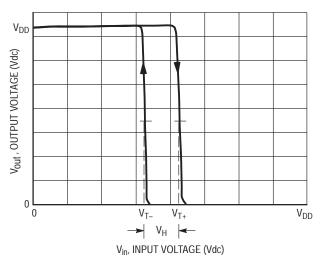
Figure 1. Switching Time Test Circuit and Waveforms



(a) Schmitt Triggers will square up inputs with slow rise and fall times.

(b) A Schmitt trigger offers maximum noise immunity in gate applications.

Figure 2. Typical Schmitt Trigger Applications

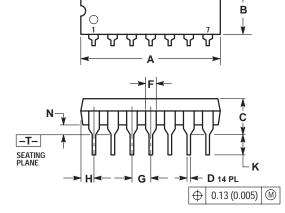


**Figure 3. Typical Transfer Characteristics** 

### **PACKAGE DIMENSIONS**

### **P SUFFIX**

PLASTIC DIP PACKAGE CASE 646-06 **ISSUE M** 

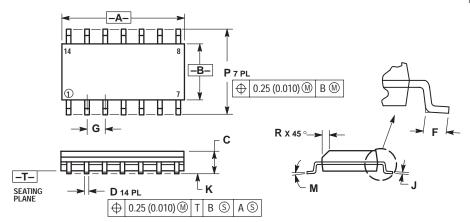




- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. CONTROLLING DIMENSION: INCH.
- DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
   DIMENSION B DOES NOT INCLUDE MOLD FLASH.
- 5. ROUNDED CORNERS OPTIONAL.

	INCHES		MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.715	0.770	18.16	18.80
В	0.240	0.260	6.10	6.60
С	0.145	0.185	3.69	4.69
D	0.015	0.021	0.38	0.53
F	0.040	0.070	1.02	1.78
G	0.100	BSC	2.54 BSC	
Н	0.052	0.095	1.32	2.41
J	0.008	0.015	0.20	0.38
K	0.115	0.135	2.92	3.43
L	0.290	0.310	7.37	7.87
М		10°		10°
N	0.015	0.039	0.38	1.01

### **D SUFFIX** PLASTIC SOIC PACKAGE CASE 751A-03 ISSUE F



### NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI
  Y14.5M, 1982.

- Y14.5M, 1982.

  2. CONTROLLING DIMENSION: MILLIMETER.

  3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.

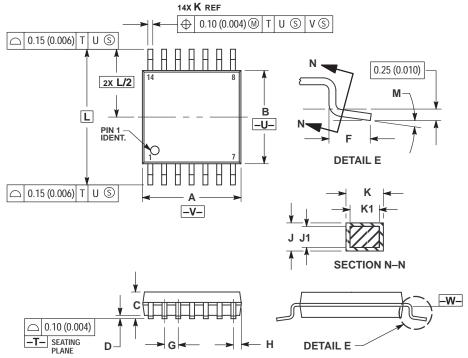
  4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.

  5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

MILLIMETERS		INC	HES
MIN	MAX	MIN	MAX
8.55	8.75	0.337	0.344
3.80	4.00	0.150	0.157
1.35	1.75	0.054	0.068
0.35	0.49	0.014	0.019
0.40	1.25	0.016	0.049
1.27	BSC	0.050	BSC
0.19	0.25	0.008	0.009
0.10	0.25	0.004	0.009
0 °	7°	0°	7°
5.80	6.20	0.228	0.244
0.25	0.50	0.010	0.019
	MIN 8.55 3.80 1.35 0.35 0.40 1.27 0.19 0.10 0° 5.80	8.55 8.75 3.80 4.00 1.35 1.75 0.35 0.49 0.40 1.25 1.27 BSC 0.19 0.25 0.0 0.25 0 7 ° 5.80 6.20	MIN         MAX         MIN           8.55         8.75         0.337           3.80         4.00         0.150           1.35         1.75         0.054           0.35         0.49         0.014           0.40         1.25         0.016           1.27 BSC         0.055         0.008           0.19         0.25         0.008           0.10         0.25         0.004           0 ° 7 °         0 ° 0         0           5.80         6.20         0.228

### **PACKAGE DIMENSIONS**

### **DT SUFFIX** PLASTIC TSSOP PACKAGE CASE 948G-01 **ISSUE O**



- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- Y14.5M, 1982.

  CONTROLLING DIMENSION: MILLIMETER.

  DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED
- 0.15 (0.006) PER SIDE.

  4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION.
  INTERLEAD FLASH OR PROTRUSION SHALL NOT
- INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.

  5. DIMENISION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.03) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.

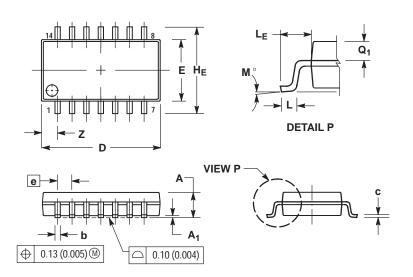
  6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.

  7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE.

DETERMINED AT DATHM PLANE -W-						
DETE	MILLIMETERS			HĖS		
DIM	MIN	MAX	MIN	MAX		
Α	4.90	5.10	0.193	0.200		
В	4.30	4.50	0.169	0.177		
С		1.20		0.047		
D	0.05	0.15	0.002	0.006		
F	0.50	0.75	0.020	0.030		
G	0.65	BSC	0.026 BSC			
Н	0.50	0.60	0.020	0.024		
J	0.09	0.20	0.004	0.008		
J1	0.09	0.16	0.004	0.006		
K	0.19	0.30	0.007	0.012		
K1	0.19	0.25	0.007	0.010		
L	6.40 BSC		0.252	BSC		
M	0 °	8°	0°	8°		

### PACKAGE DIMENSIONS

# F SUFFIX PLASTIC EIAJ SOIC PACKAGE CASE 965-01 ISSUE O



### NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI
   V14 5M 1982
- 2. CONTROLLING DIMENSION: MILLIMETER
- DIMENSIONS D AND E DO NOT INCLUDE
  MOLD FLASH OR PROTRUSIONS AND ARE
  MEASURED AT THE PARTING LINE. MOLD FLASH
  OR PROTRUSIONS SHALL NOT EXCEED 0.15
  (0.006) PER SIDE.

   TERMINAL NUMBERS ARE SHOWN FOR
- 5. THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

	MILLIN	METERS	INC	HES	
DIM	MIN	MAX	MIN	MAX	
Α		2.05		0.081	
A <sub>1</sub>	0.05	0.20	0.002	0.008	
b	0.35	0.50	0.014	0.020	
С	0.18	0.27	0.007	0.011	
D	9.90	10.50	0.390	0.413	
Ε	5.10	5.45	0.201	0.215	
е	1.27	BSC	0.050 BSC		
HE	7.40	8.20	0.291	0.323	
0.50	0.50	0.85	0.020	0.033	
LE	1.10	1.50	0.043	0.059	
M	0 °	10 °	0°	10 °	
Q <sub>1</sub>	0.70	0.90	0.028	0.035	
Z		1.42		0.056	

ON Semiconductor and are trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILC and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer.

### **PUBLICATION ORDERING INFORMATION**

### NORTH AMERICA Literature Fulfillment:

Literature Distribution Center for ON Semiconductor P.O. Box 5163, Denver, Colorado 80217 USA

**Phone**: 303–675–2175 or 800–344–3860 Toll Free USA/Canada **Fax**: 303–675–2176 or 800–344–3867 Toll Free USA/Canada

Email: ONlit@hibbertco.com

Fax Response Line: 303-675-2167 or 800-344-3810 Toll Free USA/Canada

N. American Technical Support: 800-282-9855 Toll Free USA/Canada

**EUROPE:** LDC for ON Semiconductor – European Support

German Phone: (+1) 303-308-7140 (M-F 1:00pm to 5:00pm Munich Time)

Email: ONlit-german@hibbertco.com

French Phone: (+1) 303–308–7141 (M–F 1:00pm to 5:00pm Toulouse Time)

Email: ONlit-french@hibbertco.com

**English Phone**: (+1) 303–308–7142 (M–F 12:00pm to 5:00pm UK Time)

Email: ONlit@hibbertco.com

EUROPEAN TOLL-FREE ACCESS\*: 00-800-4422-3781

\*Available from Germany, France, Italy, England, Ireland

### CENTRAL/SOUTH AMERICA:

Spanish Phone: 303-308-7143 (Mon-Fri 8:00am to 5:00pm MST)

Email: ONlit-spanish@hibbertco.com

ASIA/PACIFIC: LDC for ON Semiconductor – Asia Support

Phone: 303-675-2121 (Tue-Fri 9:00am to 1:00pm, Hong Kong Time)

Toll Free from Hong Kong & Singapore: 001–800–4422–3781

Email: ONlit-asia@hibbertco.com

JAPAN: ON Semiconductor, Japan Customer Focus Center 4–32–1 Nishi–Gotanda, Shinagawa–ku, Tokyo, Japan 141–8549

Phone: 81–3–5740–2745 Email: r14525@onsemi.com

ON Semiconductor Website: http://onsemi.com

For additional information, please contact your local Sales Representative.